

The documentation and process conversion measures necessary to comply with this revision shall be completed by 15 Jan 93.

INCH-POUND

MIL-S-19500/124G
 15 October 1992
 SUPERSEDING
 MIL-S-19500/124F
 1 August 1980

MILITARY SPECIFICATION

SEMICONDUCTOR DEVICE, DIODE, SILICON, VOLTAGE REGULATOR B AND RB
 TYPES 1N2970 THROUGH 1N2977, 1N2979, 1N2980, 1N2982, 1N2984
 THROUGH 1N2986, 1N2988 THROUGH 1N2993, 1N2995, 1N2997, 1N2999
 THROUGH 1N3005, 1N3007, 1N3008, 1N3009, 1N3011, 1N3012, 1N3014, 1N3015,
 A AND RA TYPES 1N3993 THROUGH 1N3998, JAN, JANTX, JANTXV, AND JANS

This specification is approved for use by all Departments and Agencies of the Department of Defense.

1. SCOPE

1.1 Scope. This specification covers the detail requirements for 10 watt, silicon, voltage regulator diodes: A or B type (standard polarity); RA or RB type (reverse polarity). Four levels of product assurance are provided for each device type as specified in MIL-S-19500.

1.2 Physical dimensions. See figure 1 (DD-4).

1.3 Maximum ratings. (maximum ratings are as shown in columns 4, 8, and 10 of table V herein and as follows:

$$\begin{aligned} -65^{\circ}\text{C} \leq T_J \leq +175^{\circ}\text{C}; P_T &= 10 \text{ W at } T_C = +55^{\circ}\text{C}; \text{ derate at } .083 \text{ W}/^{\circ}\text{C} \text{ above } +55^{\circ}\text{C}. \\ -65^{\circ}\text{C} \leq T_{STG} \leq +200^{\circ}\text{C}. \end{aligned}$$

1.4 Primary electrical characteristics. Primary electrical characteristics are as shown in columns 2, 9, 12, and 14 of table V herein, and as follows:

$$\text{Thermal resistance } (R_{\theta JC}) = 12^{\circ}\text{C}/\text{W maximum.}$$

2. APPLICABLE DOCUMENTS

2.1 Government documents.

2.1.1 Specifications, standards, and handbooks. The following specifications, standards, and handbooks form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DODISS) and supplement thereto, cited in the solicitation (see 6.2).

Beneficial comments (recommendations, additions, deletions) and any pertinent data which may be of use in improving this document should be addressed to U.S. Army Laboratory Command Electronics Technology and Devices Laboratory ATTN: SLCET-RS Fort Monmouth, NJ 07703-5601 by using the Standardization Document Improvement Proposal (DD Form 1426) appearing at the end of this document or letter

AHSC N/A

FSC 5961

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MIL-S-19500/124G

SPECIFICATIONS

MILITARY

MIL-S-19500 - Semiconductor Devices, General Specification for.

STANDARDS

MILITARY

MIL-STD-750 - Test Methods for Semiconductor Devices.

(Unless otherwise indicated, copies of federal and military specifications, standards, and handbooks are available from the Standardization Documents Order Desk, Building 4D, 700 Robbins Avenue, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this document and the references cited herein, the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Associated detail specification. The individual item requirements shall be in accordance with MIL-S-19500, and as specified herein.

3.2 Abbreviations, symbols, and definitions. Abbreviations, symbols, and definitions used herein shall be as specified in MIL-S-19500.

3.3 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-S-19500 and on figure 1 herein.

- a. Device types 1N2970B through 1N3015B and 1N3993RA through 1N3998RA shall have the anode connected to the stud.
- b. Device types 1N2970RB through 1N3015RB and 1N3993A through 1N3998A shall have the cathode connected to the stud.

3.3.1 Lead finish. Lead finish shall be gold, silver, or tin-lead plated. Where a choice of lead finish is desired, it shall be specified in the acquisition document (see 6.2).

3.4 Marking. Devices shall be marked in accordance with MIL-S-19500. At the option of the manufacturer, the marking of the country of origin may be omitted from the body of the diodes, but shall be retained on the initial container.

3.4.1 Reverse polarity types. Reverse polarity units (see 3.3a and b) shall be marked with an "R" preceding the "A" or "B" in the type designation, as applicable.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection shall be in accordance with MIL-S-19500, and as specified herein.

4.2 Qualification inspection. Qualification inspection shall be in accordance with MIL-S-19500 and as specified herein.

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4.3 Screening (JANS, JANTX, and JANTXV levels only). Screening shall be in accordance with table II of MIL-S-19500, and as specified herein. The following measurements shall be made in accordance with table I herein. Devices that exceed the limits of table I herein shall not be acceptable.

| Screen (see table II of MIL-S-19500) | Measurement | |
|--------------------------------------|--|--|
| | JANS level | JANTX and JANTXV levels |
| 7(b) | MIL-STD-750, test method 1071, condition C, step 2. | MIL-STD-750, test method 1071, condition C, step 2. |
| 9 | I_R and V_Z (for devices with $V_{Z(nom)} \geq 10$ V dc; see column 2 of table V). | Not applicable |
| 11 | I_R and V_Z ; $\Delta I_R = 100\%$ of initial value or 1 of column 12 of table V, whichever is greater; $\Delta V_Z = \pm 2.5\%$ of initial value (for devices with $V_{Z(nom)} \geq 10$ V dc; see column 2 of table V). | I_R and V_Z |
| 12 | See 4.3.1 | See 4.3.1 |
| 13 | Subgroups 2, 3, and 4 of table I herein; $\Delta I_R = 100\%$ of initial value or 1 of column 12 of table V, whichever is greater; $\Delta V_Z = \pm 2.5\%$ of initial value. | Subgroup 2 of table I herein; $\Delta I_R = 100\%$ of initial value or 1 of column 12 of table V, whichever is greater; $\Delta V_Z = \pm 2.5\%$ of initial value. |

4.3.1 Power burn-in conditions. Power burn-in conditions are as follows:

$I_Z =$ Column 15 of table V; $V_Z =$ Column 2 of table V; $T_C = 150 \pm 5^\circ\text{C}$.

4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-S-19500 and as specified herein. Group A inspection shall be performed on each subplot.

4.4.1 Group A inspection. Group A inspection shall be conducted in accordance with MIL-S-19500 and table I herein. End point electrical measurements shall be in accordance with the applicable steps of table IV herein.

4.4.2 Group B inspection. Group B inspection shall be conducted in accordance with the conditions specified for subgroup testing in table IVa (JANS) and table IVb (JAN, JANTX, and JANTXV), of MIL-S-19500, and tables IIa and IIb herein. Electrical measurements (end points) and delta requirements shall be in accordance with the applicable steps of table IV herein.

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TABLE I. Group A inspection.

| Inspection ^{1/} | MIL-STD-750 | | Symbol | Limits ^{2/} | | Unit |
|--|-------------|---|---------------------|----------------------|-----------|------------------|
| | Method | Conditions | | Min | Max | |
| <u>Subgroup 1</u> | | | | | | |
| Visual and mechanical inspection | 2071 | | | | | |
| <u>Subgroup 2</u> | | | | | | |
| Forward voltage | 4011 | $I_F = 2 \text{ A dc}$ | V_F | | 1.5 | V dc |
| Reverse current | 4016 | $V_R = \text{column 11 of table V, dc method}$ | I_{R1} | | Column 12 | A dc |
| Regulator voltage (see 4.5.3) | 4022 | $I_Z = \text{column 5 of table V}$ | V_Z | Column 3 | Column 4 | V dc |
| <u>Subgroup 3</u> | | | | | | |
| High temperature operation | | $T_A = 150^\circ\text{C}$ | | | | |
| Reverse current | 4016 | dc method $V_R = \text{column 11 of table V}$ | I_{R2} | | 500 | $\mu\text{A dc}$ |
| <u>Subgroup 4</u> | | | | | | |
| Small-signal breakdown impedance | 4051 | $I_Z = \text{column 5 of table V; } I_{\text{sig}} = 10\% I_{Z\text{rms}}$ | Z_Z | | Column 6 | ohms |
| Knee impedance | 4051 | $I_{ZK} = 1 \text{ mA dc, } I_{\text{sig}} = 10\% I_{ZK\text{rms}}$ | Z_{ZK} | | Column 7 | ohms |
| <u>Subgroup 5</u> | | | | | | |
| Not applicable | | | | | | |
| <u>Subgroup 6</u> | | | | | | |
| Surge current (see 4.5.1) | 4066 | $T_C = 25^\circ\text{C; } I_{ZSM} = \text{column 10 of table V}$ | | | | |
| End point electrical measurements | | See table IV, steps 1, 3, and 4 | | | | |
| <u>Subgroup 7</u> | | | | | | |
| Voltage regulation (see 4.5.2) | | | $V_{Z(\text{reg})}$ | | Column 9 | V dc |
| Temperature coefficient of breakdown voltage (see 4.5.4) | 4071 | $I_Z = \text{column 5 of table V; } T_1 = 30^\circ\text{C; } T_2 = T_1 + 100^\circ\text{C}$ | αV_Z | | Column 14 | $^\circ\text{C}$ |

^{1/} For sampling plan, see MIL-S-19500.^{2/} Column references are to table V herein.

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TABLE IIa. Group B inspection for JANS devices.

| Inspection ^{1/} | MIL-STD-750 | |
|--|-------------|---|
| | Method | Conditions |
| <u>Subgroup 1</u> | | |
| Physical dimensions | 2066 | See figure 1 |
| <u>Subgroup 2</u> | | |
| Solderability | 2026 | Dwell time = 10 ±1 s; immersion to cover flat portion of terminal only |
| Resistance to solvents | 1022 | |
| <u>Subgroup 3</u> | | |
| Thermal shock (temperature cycling) | 1051 | |
| Hermetic seal | 1071 | |
| a. Fine | | |
| b. Gross | | |
| Electrical measurements | | See table IV, steps 1, 3, 4, 5, and 6 |
| Die shear | 2017 | |
| <u>Subgroup 4</u> | | |
| Intermittent operating life | 1037 | I_Z = column 8 of table V, $t_{on} = t_{off}$ = 3 minutes minimum for 2,000 cycles. $T_C = 30 \pm 3^\circ\text{C}$ |
| Electrical measurements | | See table IV, steps 1, 3, 4, 5, and 6 |
| <u>Subgroup 5</u> | | |
| Accelerated steady - state operation life | 1027 | I_Z = column 15 of table V for 96 hours, $T_A = 125^\circ\text{C}$ or adjusted, as required, to give an average lot $T_J = 225^\circ\text{C}$ |
| Electrical measurements | | See table IV, steps 2, 3, 4, 5, and 6 |
| <u>Subgroup 6</u> | | |
| Thermal resistance | 4081 | $R_{\theta JC} = 12^\circ\text{C/W}$ maximum, $T_C = 30 \pm 3^\circ\text{C}$. For purposes of this test "junction to case" shall be used in lieu of "junction to lead" and " $R_{\theta JC}$ " shall be used in lieu of " $R_{\theta JL}$ ". The case shall be the reference point for calculation of junction to case thermal resistance ($R_{\theta JC}$). The mounting arrangement shall be with heat sink to case. |

^{1/} For sampling plan, see MIL-S-19500.

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TABLE IIb. Group B inspection for JAN, JANTX, and JANTXV devices.

| Inspection ^{1/} | MIL-STD-750 | |
|--|-------------|--|
| | Method | Conditions |
| <u>Subgroup 1</u> | | |
| Solderability | 2026 | Dwell time = 10 ±1 s; immersion to cover flat portion of terminal only |
| Resistance to solvents | 1022 | |
| <u>Subgroup 2</u> | | |
| Thermal shock (temperature cycling) | 1051 | |
| Surge current (see 4.5.1) | | I_{ZSM} = column 10 of table V |
| Hermetic seal | 1071 | |
| a. Fine leak b. Gross leak | | |
| Electrical measurements | | See table IV, steps 1, 3, and 4 |
| <u>Subgroup 3</u> | | |
| Steady-state operation life | 1027 | I_Z = column 15 of table V T_C = 150 ±5°C |
| Electrical measurements | | See table IV, steps 2, 3, and 4 |
| <u>Subgroup 4</u> | | |
| Decap internal visual (design verification) | 2075 | |
| <u>Subgroup 5</u> | | |
| Thermal resistance | 4081 | $R_{\theta JC}$ = 12°C/W maximum; T_C = 30 ±3°C. For purposes of this test "junction to case" shall be used in lieu of "junction to lead" and " $R_{\theta JC}$ " shall be used in lieu of " $R_{\theta JL}$ ". The case shall be the reference point for calculation of junction to case thermal resistance ($R_{\theta JC}$). The mounting arrangement shall be with heatsink to case. |
| <u>Subgroup 6</u> | | |
| High temperature (non- operating life) | 1032 | T_A = 200°C |
| Electrical measurements | | See table IV, steps 2, 3, and 4 |

^{1/} For sampling plan, see MIL-S-19500.

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TABLE III. Group C inspection for all quality levels.

| Inspection 1/ | MIL-STD-750 | | Symbol | Limits | | Unit |
|----------------------------------|-------------|--|--------|--------|-----|------|
| | Method | Conditions | | Min | Max | |
| <u>Subgroup 1</u> | | | | | | |
| Physical dimensions | 2066 | See figure 1 | | | | |
| <u>Subgroup 2</u> | | | | | | |
| Thermal shock (glass strain) | 1056 | | | | | |
| Terminal strength | 2036 | | | | | |
| Tension | | Test condition A; 20 pounds; t = 15 ±3 s | | | | |
| Torque (terminal) | | Test condition D ₁ ; 10 ounce-inches; t = 15 ±3 s | | | | |
| Torque (stud) | | Test condition D ₂ ; 15 pound-inches; t = 30 ±3 s | | | | |
| Bending stress | | Test condition F; 3 pounds; t = 15 ±3 s, method B. | | | | |
| Hermetic seal | 1071 | | | | | |
| a. Fine leak | | | | | | |
| b. Gross leak | | | | | | |
| Moisture resistance | 1021 | | | | | |
| Electrical measurements | | See table IV, steps 1, 3, 4, 5, and 6 (JANS) and steps 1, 3, and 4 (JAN, JANTX, and JANTXV) | | | | |
| <u>Subgroup 3</u> | | | | | | |
| Shock | 2016 | | | | | |
| Vibration, variable frequency | 2056 | | | | | |
| Constant acceleration | 2006 | | | | | |
| Electrical measurements | | See table IV, steps 1, 3, 4, 5, and 6 (JANS) and steps 1, 3, and 4 (JAN, JANTX and JANTXV) | | | | |
| <u>Subgroup 4</u> | | | | | | |
| Salt atmosphere (corrosion) | 1041 | | | | | |

See footnotes at end of table.

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TABLE III. Group C inspection for all quality levels) - Continued.

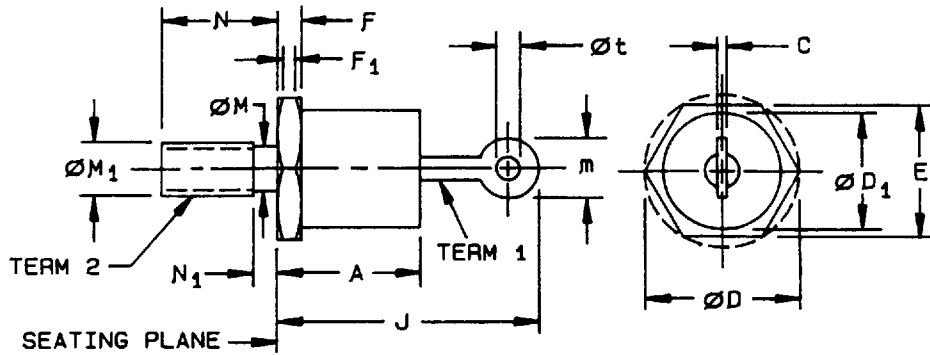
| Inspection ^{1/} | MIL-STD-750 | | Symbol | Limits | | Unit |
|---|-------------|---|-------------------|--------|-----------------------|------|
| | Method | Conditions | | Min | Max | |
| <u>Subgroup 5</u> ^{2/} Barometric pressure reduced (altitude operation) | 1001 | 8 mm Hg | | | | |
| <u>Subgroup 6</u> Steady-state operation life Electrical measurements | 1026 | I_Z = column 15 of table IV T_C = +150 ±5°C See table IV, steps 2, 3, 4, 5, and 6 (JANS) and steps 2, 3, and 4 (JAN, JANTX, and JANTXV) | | | | |
| <u>Subgroup 7</u> ^{3/} Temperature coefficient of breakdown voltage (see 4.5.3) | 4071 | JAN, JANTX, and JANTXV levels only I_Z = column 5 of table V T_1 = 30 ±3°C; T_2 = T_1 +100°C each subplot | αV_Z | | Column 14 of table IV | /°C |
| Voltage regulation (see 4.5.2) | | Each subplot | $V_Z(\text{reg})$ | | Column 9 of table V | V dc |

^{1/} For sampling plan, see MIL-S-19500.^{2/} LTPD = 15, small lot = 6 devices, c = 0.^{3/} LTPD = 10, small lot = 12 devices, c = 0.

Page(s) 9 + 10 of this document was (were)
missing upon receipt. The document has been reordered
and will be refilmed when received.

INFORMATION HANDLING SERVICES

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| Symbol | Dimensions | | | | Notes |
|------------|------------|------|-------------|-------|-------|
| | Inches | | Millimeters | | |
| | Min | Max | Min | Max | |
| A | .300 | .405 | 7.62 | 10.29 | |
| C | .012 | .065 | .30 | 1.65 | |
| ϕD | ---- | .505 | ---- | 12.83 | |
| ϕD_1 | .255 | .424 | 6.48 | 10.77 | |
| E | .423 | .438 | 10.74 | 11.13 | |
| F | .075 | .175 | 1.90 | 4.44 | |
| F_1 | .060 | .175 | 1.52 | 4.44 | 2 |
| J | .600 | .800 | 15.24 | 20.32 | |
| ϕM | .163 | .189 | 4.14 | 4.80 | 1 |
| ϕM_1 | ---- | ---- | ---- | ---- | 5 |
| m | ---- | .250 | ---- | 6.35 | 3 |
| N | .422 | .453 | 10.72 | 11.51 | |
| N_1 | ---- | .078 | ---- | 1.98 | 4 |
| ϕt | .060 | .095 | 1.52 | 2.41 | |
| W | ---- | ---- | ---- | ---- | |

NOTES:

1. Complete threads to extend to within 2-1/2 threads of seating plane.
2. Chamfer on undercut on one or both ends of hexagonal base is optional.
3. Angular orientation of this terminal is undefined.
4. Length of incomplete or undercut threads of ϕM .
5. 10-32 UNF-2A maximum pitch diameter of plated threads shall be basic pitch diameter (.1697 inch (4.310 mm)) reference. (Screw thread standards for Federal Services 1957) Handbook H28 P1.
6. Metric equivalents are given for general information only.

FIGURE 1. Physical dimensions.

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4.4.3 Group C inspection. Group C inspection shall be conducted in accordance with the conditions specified for subgroup testing in table V of MIL-S-19500 and table III herein. Electrical measurements (end points) and delta requirements shall be in accordance with the applicable steps of table IV herein.

4.5 Methods of inspection. Methods of inspection shall be as specified in the appropriate tables and as follows:

4.5.1 Surge current I_{ZSM} . The currents specified in column 10 of table V shall be applied in the reverse direction and shall be superimposed on the current (I_Z = column 5 of table V) a total of five surges at 1-minute intervals. Each individual surge shall be a 1/2 square wave pulse of 1/120-second duration or an equivalent 1/2 sine wave with the same effective (rms) current.

4.5.2 Voltage regulation $V_Z(\text{reg})$. A current at 10 percent of I_{ZM} (column 8) shall be maintained until thermal equilibrium is obtained, and the I_Z shall then be increased to a level of 50 percent of I_{ZM} (column 8) and maintained at this level for a period of time until thermal equilibrium is obtained at which time the voltage change shall not exceed column 9 of table V. During this test, the case temperature (T_C) of the diode shall be equal to $30 \pm 3^\circ\text{C}$.

4.5.3 Regulator voltage. The I_Z test current (column 5 of table V) shall be applied until thermal equilibrium is obtained prior to reading the regulator voltage. During this test, the case temperature (T_C) of the diode shall be equal to $30 \pm 3^\circ\text{C}$.

4.5.4 Temperature coefficient of regulator voltage (αV_Z). The device shall be temperature stabilized with current applied prior to reading regulator voltage at the specified case temperatures.

4.5.5 Inspection condition. Unless otherwise specified in MIL-S-19500 or herein, all inspections shall be made at case temperature (T_C) of $30 \pm 3^\circ\text{C}$.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-S-19500.

6. NOTES

6.1 Notes. The notes specified in MIL-S-19500 are applicable to this specification.

6.2 Ordering data. Procurement documents should specify the following:

- a. Lead material and finish (see 3.2.1).
- b. Type designation, polarity type, and product assurance level.

6.3 Part number information. Part numbers 1N3993A, RA through 1N3998A, and RA from MIL-S-19500/272 have been incorporated into MIL-S-19500/124.

6.4 Changes from previous issue. Asterisks are not used in this revision to identify changes with respect to the previous issue, due to the extensiveness of the changes.

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Custodians:

Army - ER
Navy - EC
Air Force - 17
NASA - NA

Review activities:

Army - AR, MI
Navy - SH
Air Force - 11, 19, 85
DLA - ES
NASA - LRC, MSF

User activities:

Army - SM
Navy - AS, CG, MC, OS
Air Force - 13

Preparing activity:

Army - ER

Agent:

DLA - ES

(Project 5961-1365)